Chip Scale REVIEW®

EDITORIAL CALENDAR
(Eight issues in 2003)

Issue	Issue Emphasis	Editor's Reports	Special Feature with Vendor Directory	Tutorial	• Show Distribution ➧ Space Close (Materials Close)
January-February	• Dispensing, encapsulation and underfill • Wafer probing	• Dispensing trends • Wafer probing • New directions in underfills	• Dispensing systems • Wafer probing equipment	• Wafer probing	• SEMICON Korea, Jan. 21-23 Seoul • BiTS Conference, March 2-5 Mesa, Ariz. ➧ *Nov. 22 (Nov. 29)*
March	• Flip-chip packaging • Opto packaging	• Equipment, consumables and strategies for optoelectronic packaging • How thermal considerations in IC packaging affect the bottom line • Flip-chip packaging for the next generation • Selecting adhesives for IC packaging • Stencil preparation and cleaning	• Flip-chip bonders • Stencil printers	• Basic optoelectronic packaging	• SEMICON China, March 11-13 Shanghai • OFC, March 25-27 Atlanta, Ga. • APEX, March 31-April 2 Anaheim, Calif. • SEMICON Europa, April 1-3 Munich, Germany ➧ *Jan. 22 (Jan. 29)*
April	• Test sockets • Final test	• Test sockets: New ideas and new challenges • How final test impacts the assembly line • Testing considerations for Bluetooth devices	• RF ATE vendors • Socket vendors	• Final test	• SEMICON Singapore, May 6-8 Singapore ➧ *Feb. 21 (Feb. 28)*
May-June	• Annual IC packaging foundry issue • Package and wafer marking	• IC assembly trends • How front-end/back-end convergence will affect the IC assembly industry • Package and wafer-marking trends • Molding compounds	• Packaging foundries • Package and wafer-marking equipment	• Wafer mapping	• ECTC, May 27-30 New Orleans, La. ➧ *March 31 (April 7)*
July	• Wafer-bumping and wafer-level packaging • 3D, SoCs/SiPs and stacked packages	• Seam-sealing equipment trends • Low-k materials • Lithography systems for wafer-level packaging • Package substrate materials	• Wafer bumping service providers • Seam-sealing equipment	• Low-k materials	• SEMICON West, July 16-18 San Jose ➧ *May 23 (May 30)*
August	• Singulation • Handling, packing and transporting media	• Making the perfect cut: Selecting between saws, punches and laser-based tools • Media for handling, packing, transporting and shipping wafers and packaged ICs • Lead scanners and straighteners	• Singulation: Saws, punches and laser tools • Media for transporting and shipping products	• Wafer thinning and backgrinding	• KGD Workshop, Sept. 8-10 Napa, Calif. ➧ *July 2 (July 12)*
September-October	• Acoustic and X-Ray Inspection (AXI) • Solder	• Temperature profiling • X-ray inspection: Out of the lab and into the mainstream • Solder ball placement equipment trends • Solder reflow	• AXI equipment • Solder ball placement systems	• Solder ball placement	• SEMICON Taiwan, Sept. 15-17 Taipei • SMTA International, Sept. 22-26 Chicago • Fabless Semiconductor Show October, Date Pending Santa Clara, Calif. ➧ *August 5 (August 12)*
November-December	• Package inspection, Part 2 Automated Optical Inspection (AOI) • Update: Test & burn-in sockets	• Cleaning systems • The Editorial Advisors forecast 2004 • Sockets aim at new high-speed applications • Automated optical inspection (and laser inspection) for failure analysis of IC packages	• Acoustic, AOI and Laser-based inspection systems • Socket Update	• AOI Applications in IC packaging	• IMAPS 2003, Nov. 18-20 Boston ➧ *Oct. 4 (Oct. 11)*

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